L4 ANSWER 1 OF 1 CAPLUS COPYRIGHT 2000 ACS
AN 1984:572633 CA[redacted]
DN 101:172633
TI Electric cable with crosslinked polyethylene insulation
PA Sumitomo Electric Industries, Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 3 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
IC H01B003-44; H01B007-00
CC 38-3 (Plastics Fabrication and Uses)
FAN.CNT 1

| PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
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| PI JP 59099611 | A2 | 19840608 | JP 1982-210090 | 19821130 <-- |

AB The cable uses low-d. polyethylene [9002-88-4] for which the ratio of wt.-av. mol. wt. to no.-av. mol. wt. is .ltoreq.5. Preferably, the polymer is crosslinked by a dry method and the insulation thickness is .gtoreq.7 mm, and there may be a metallic waterproof layer. The cable provides much improved weatherability. Thus, low-d. polyethylene (ratio 4) was mixed with 2,5-dimethyl-2,5-bis(tert-butylperoxy)hexane [78-63-7], extruded to form the insulator layer of the cable, and heated by IR irradn. for crosslinking. Comparative tests showed increased durability.

======= WPI =======

TI - Near infrared radiation-setting foam resin compsn. - contains addn. polymerisable ethylenically unsatd. cpd., initiator and hollow filler(s)

AB - J06192459 The compsn. contains an addn.-polymerisable ethylenically unsatd. cpd., a near infrared radiation polymerisation initiator and hollow filler(s) or thermally expansive microcapsules.
- The addn. polymerisable ethylenically unsatd. cpd. is a (meth)acrylic ester of monohydric or polyhydric alcohol or a methacrylic ester. The hollow filler(s) of up to 300 microns grain size comprise(s) silica, glass, carbon or alumina. The thermally expansive microcapsules composed of vinylidene chloride-acrylonitrile copolymer include a low b.pt. solvent such as isobutylene.
- USE/ADVANTAGE - The compsn. can be hardened in a short time by irradiation with near infrared. The foamed hardened resin compsn. is used as an adiabatic coating material for refrigerant, an insulator for the wall of a house, a gasket or a sealant. (Dwg.0/0)

PN - JP6192459 A 19940712 DW199432 C08J9/14 006pp
PR - JP19920357728 19921225
PA - (TOKT ) TOKYO THREE BOND CO LTD
MC - A02-A09 A04-D03 A04-E07 A04-F06E A08-R01 A12-S04B G02-A05 G04-B01 G04-B02
DC - A14 A88 A93 G02 G04 P42
IC - B05D3/06 ;C08J9/14 ;C09D4/00 ;C09K3/10
AN - 1994-260634 [32]

======= PAJ =======

TI - NEAR-INFRARED-CURING EXPANDABLE RESIN COMPOSITION
AB - PURPOSE:To obtain a composition which can give a cured thick product upon irradiation with near-infrared rays in a short time by mixing an addition- polymerizable, ethylenically unsaturated compound with a near-infrared polymerization initiator and a hollow filler or thermally expandable microcapsules.
- CONSTITUTION:The composition is prepared by mixing an addition-polymerizable, ethylenically unsaturated compound (e.g. tetramethylolmethane trimethacrylate) with a near-infrared polymerization initiator (e.g. an aniline colorant complex of the formula) and a hollow filler (e.g. 'Shirasu' balloons or thermally expandable microcapsules). Examples of the thermally expandable microcapsule include one prepared by enclosing a low-boiling solvent such as isobutane in a microcapsule of a vinylidene chloride/ acrylinitrile copolymer. Because the near-infrared rays can permeate even to the inside of the obtained resin composition when it is irradiated with near-infrared rays, the composition can give an expanded cured product within a short time.

PN - JP6192459 A 19940712
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AP - JP19920357728 19921225
GR - C1262
PA - THREE BOND CO LTD
IN - KATSUNO NOBUHIRO
I - C08J9/14 ;B05D3/06 ;C09K3/10
SI - C09D4/00